

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM458768

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	Termination and Release of Trademark and Patent Security Agreement recorded at Reel 3877/Frame 0091		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
BHC Interim Funding II, L.P.		01/16/2018	Limited Partnership: DELAWARE
RECEIVING PARTY DATA			
Name:	Wafer Holdings, Inc.		
Street Address:	6330 Hedgewood Drive, Suite 150		
City:	Allentown		
State/Country:	PENNSYLVANIA		
Postal Code:	18106		
Entity Type:	Corporation: DELAWARE		
PROPERTY NUMBERS Total: 6			
Property Type	Number	Word Mark	
Registration Number:	2993100	LUCID2	
Registration Number:	2295797	GOLDFINGER	
Registration Number:	2040148	VERTEQ	
Registration Number:	2691082	AKRION	
Registration Number:	1598327	SUBMICRON	
Registration Number:	1574491	SUNBURST	
CORRESPONDENCE DATA			
Fax Number:	9494754754		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	949-451-3800		
Email:	skann@gibsondunn.com		
Correspondent Name:	Stephanie Kann		
Address Line 1:	3161 Michelson Drive		
Address Line 2:	Gibson, Dunn & Crutcher LLP		
Address Line 4:	Irvine, CALIFORNIA 92612		
ATTORNEY DOCKET NUMBER:	12833-00001		
NAME OF SUBMITTER:	Stephanie Kann		

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SIGNATURE:	/stephanie kann/
DATE SIGNED:	01/19/2018
Total Attachments: 8 source=40. Termination and Release of IP Security - (BHC - Wafer) (Executed)#page1.tif source=40. Termination and Release of IP Security - (BHC - Wafer) (Executed)#page2.tif source=40. Termination and Release of IP Security - (BHC - Wafer) (Executed)#page3.tif source=40. Termination and Release of IP Security - (BHC - Wafer) (Executed)#page4.tif source=40. Termination and Release of IP Security - (BHC - Wafer) (Executed)#page5.tif source=40. Termination and Release of IP Security - (BHC - Wafer) (Executed)#page6.tif source=40. Termination and Release of IP Security - (BHC - Wafer) (Executed)#page7.tif source=40. Termination and Release of IP Security - (BHC - Wafer) (Executed)#page8.tif	

**TERMINATION AND RELEASE OF TRADEMARK AND PATENT SECURITY
AGREEMENT**

THIS TERMINATION AND RELEASE OF TRADEMARK AND PATENT SECURITY AGREEMENT (this "Termination"), is dated as of January 16, 2018, and made by **BHC INTERIM FUNDING II, L.P.** (the "Grantee"), to **WAFER HOLDINGS, INC.**, a Delaware corporation (the "Grantor").

WHEREAS, pursuant to that certain (i) Term Loan and Security Agreement, dated as of September 26, 2008 (as amended, restated or otherwise modified through the date hereof, the "Security Agreement"); and (ii) Trademark and Patent Security Agreement, dated as of September 26, 2008 (as amended, restated or otherwise modified through the date hereof, the "Trademark and Patent Security Agreement"), made by Grantor in favor of Grantee, a security interest was granted by the Grantor to Grantee in certain collateral, including the Trademarks and Patents (as hereinafter defined);

WHEREAS, the Trademark and Patent Security Agreement was recorded with the trademark division of the United States Patent and Trademark Office on October 27, 2008 at Reel 003877, Frame 0091, and with the patent division of the United States Patent and Trademark Office on October 27, 2008 at Reel 021731, Frame 0718; and

WHEREAS, Grantee now desires to terminate and release the Security Agreement and Trademark and Patent Security Agreement;

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy of which are hereby acknowledged, and upon the terms set forth in this Termination, Grantee hereby states as follows:

1. Definitions. The terms "Trademarks" and "Patents" as used herein, shall mean all of the Grantor's right, title and interest of every kind and nature as of the date hereof in the Trademarks and Patents listed on Schedule A hereto.

2. Release of Security Interest. Grantee does hereby terminate, release and discharge the entirety of any and all liens or security interests that it may have in, and all claims, whether presently existing or hereafter acquired or created, pursuant to the Security Agreement and Trademark and Patent Security Agreement, in the Trademarks and Patents and reassigns to the person or persons legally entitled thereto all right, title and interest of Grantee in the Trademarks and Patents.

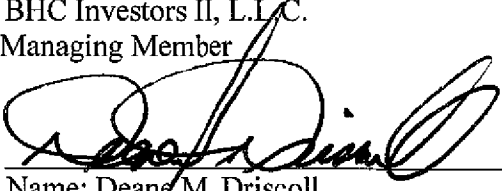
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IN WITNESS WHEREOF, the Grantee has caused this Termination to be executed by its duly authorized officer as of the date first written above.

BHC INTERIM FUNDING II, L.P.

By: BHC Interim Funding Management, L.L.C.
Its: General Partner

By: BHC Investors II, L.L.C.
Its: Managing Member

By: 
Name: Deane M. Driscoll
Title: Manager

[Signature Page to Termination and Release]

SCHEDULE A

See attached.

TRADEMARKS

LUCID2	United States of America	78/224,085	11-Mar-2003	2,993,100	06-Sep-2005
GOLDFINGER	United States of America	75/555,468	18-Sep-1998	2,295,797	30-Nov-1999
VERTEQ	United States of America	75/035,442	21-Dec-1995	2,040,148	25-Feb-1997
AKRION	United States of America	78/122,937	19-Apr-2002	2,691,082	25-Feb-2003
SUBMICRON	United States of America	73/817,473	7-Aug-1989	1,598,327	29-May-1990
SUNBURST	United States of America	73/760,371	28-Oct-1988	1,574,491	02-Jan-1990

PATENTS

Title	Country	Application Number	Application Date	Issue Date	Patent Number
Acoustic Energy System, Method Apparatus for Processing Flat Articles	US	11/625,556	1/22/2007		
Acoustic Generating Device	US	61/034,142	3/5/2008		
Apparatus and Method for Cleaning and Drying a Hydrophobic Surface of a Substrate	US	11/755,619	5/30/2007		
Apparatus and Method for the Cleaning of Substrates	US	10/111,332	4/18/2002	11/16/2004	6,817,369
Apparatus and Method for Transmitting Energy Through a Non-Reactive Transmitter Bonded to a Transducer and Use of the Same to Process Substrates	US	11/625,651	1/22/2007		
Apparatus and Method of Measuring Acoustical Energy Applied to a Substrate	US	11/837,292	8/10/2007		
Apparatus and Methods for Vapor Generation System	US	10/098,847	3/15/2002	4/20/2004	6,722,056
Apparatus for Processing Substrates in a Fluid Tank	US	09/171,757	10/23/1998	11/14/2000	6,145,520
Apparatus, System and Method for Processing a Substrate that Prohibits Air Flow Containing Contaminants and/or Residues from Depositing on the Substrate	US	11/777,256	7/12/2007		
Capillary Drying of Substrates	US	10/358,636	2/5/2003	6/21/2005	6,907,890
Centrifugal Wafer Processor	US	90/002,139	9/14/1990	1/21/1992	B1 4,571,850
Chemical Concentration Control Device	US	10/117,725	4/5/2002	7/27/2004	6,766,818
Cleaning and Drying Method and Apparatus	US	10/091,011	3/4/2002	1/4/2005	6,837,944
Compliant Silicon Wafer Handling System	US	08/825,883	4/21/1997	9/11/2001	6,286,688
Device and Method for Processing Substrates	US	09/869,213	9/22/2001	10/19/2004	6,805,754
Device and Method for the Treatment of Substrates in a Fluid Container	US	09/367,683	12/31/1999	11/18/2003	6,647,641
Device and Method for the Treating Substrates in a Fluid Container	US	08/862,890	5/23/1997	9/21/1999	5,954,068
Device for Chemical Wet Treatment	US	08/875,408	7/31/1997	5/11/1999	5,902,402
Device for Treating Substrates in a Fluid Container	US	08/761,717	12/6/1996	6/5/2001	6,240,938
Device for Wet-Treatment of Substrates	US	09/171,271	6/22/1999	8/7/2001	6,269,822
Dump Door	US	10/085,565	2/26/2002	1/18/2005	6,843,859
Facility for Treating Objects in a Process Tank	US	09/068,618	7/7/1998	2/25/2003	6,523,552
Industrial Robot Safety Device That Shuts Down Operation in Response to Variation in Tension of a Rope	US	08/851,668	5/6/1997	9/15/1998	5,807,408
Low Profile Wafer Carrier	US	10/053,449	1/17/2002	3/29/2005	6,871,657
Megasonic Cleaner and Dryer System	US	10/171,430	6/12/2002	8/16/2005	6,928,751
Megasonic Cleaner and Dryer	US	10/171,429	6/12/2002	8/2/2005	6,923,192
Megasonic Cleaner and Dryer	US	10/171,426	6/12/2002	6/29/2004	6,754,980

Title	Country	Application Number	Application Date	Issue Date	Patent Number
Megasonic Cleaner and Dryer	US	10/864,927	6/10/2002	9/5/2006	7,100,304
Megasonic Cleaner Probe System with Gasified Fluid	US	09/906,384	7/16/2001	2/3/2004	6,684,890
Megasonic Cleaner Probe System with Gasified Fluid	US	10/742,214	12/19/2003	5/23/2006	7,047,989
Megasonic Cleaner Probe System with Gasified Fluid	US	10/864,929	6/10/2004	1/2/2007	7,156,111
Megasonic Cleaner System With Buffered Cavitation Method	US	11/595,029	11/9/2006		
Megasonic Cleaning System	US	10/341,425	1/10/2003	9/1/2006	7,104,268
Megasonic Cleaning System	US	08,277,792	7/20/1994	4/29/1997	5,625,249
Megasonic Probe Energy Attenuator	US	07/791,094	11/12/1991	9/28/1993	5,247,954
Megasonic Probe Energy Attenuator	US	09/922,509	8/5/2001	1/20/2004	6,679,272
Megasonic Probe Energy Director	US	10/760,596	1/20/2004	5/17/2005	6,892,738
Megasonic Probe Energy Director	US	10/059,683	1/29/2002	10/30/2007	7,287,537
Megasonic Transducer Assembly	US	11/873,750	10/17/2007		
Megasonic System	US	08/042,889	4/5/1993	11/22/1994	5,365,960
Megasonic System	US	10/117,768	4/5/2002	3/18/2003	6,532,974
Megasonic System	US	10/304,583	1/25/2002	9/30/2003	6,626,189
Membrane Dryer	US	10/117,739	4/5/2002	1/18/2005	6,842,998
Membrane Dryer	US	10/951,009	9/22/2004	8/16/2005	6,928,750
Method and Apparatus for Drying Semiconductor Wafers	US	08/275,807	7/15/1994	9/17/1996	5,556,479
Method and Apparatus for Treating Substrates	US	09/600,084	6/30/2006	8/19/2005	6,607,604
Method and System for Chemical Injection in Silicon Wafer Processing	US	10/053,364	1/18/2002	7/27/2004	6,767,877
Method and System for Processing a Substrate Using a Composite Transmitter	US	60/985,947	11/6/2007		
Method and Systems for Determining Chemical Concentrations and Controlling the Processing of Semiconductor Substrates	US	09/257,488	2/25/1999	7/17/2001	6,261,845
Method for Cavitation Measurement	US	61/031,845	2/27/2008		
Method for Post-CMP Advanced Front End of Line Cleaning	US	12/070,620	2/19/2008		
Methods for Treating Semiconductor Wafers	US	09/096,898	6/12/1998	10/26/1999	5,972,123
Nitrogen Wet Process Tank	US	10/117,778	4/5/2002	1/11/2005	6,840,250
Nozzel for Use in the Megasonic Cleaning of Substrates	US	11/781,835	7/23/2007		
Process and Apparatus for Removal of Photoresist from Semiconductor Wafers Using Spray Nozzles	US	10/566,054	2/13/2003	11/16/2004	6,818,563
Process for Etching Oxide Films in a Sealed Photochemical Reactor	US	07/876,043	4/30/1992	8/10/1993	5,234,540
Process Sequence for Photoresist Stripping and Cleaning of Photomasks for Integrated Circuit Manufacturing	US	10/909,764	8/22/2004	1/30/2007	7,169,253
Process Sequence for Photoresist Stripping and Cleaning of Photomasks for Integrated Circuit Manufacturing	US	11/649,535	1/4/2007		

Title	Country	Application Number	Application Date	Issue Date	Patent Number
Reciprocating Megeasonic Probe	US	10/140,029	5/6/2002	3/6/2007	7,185,661
Reciprocating Megeasonic Probe	US	11/640,718	12/18/2006		
Semiconductor Wafer Cleaning System	US	08/361,139	12/21/1994	8/12/1997	5,656,097
Semiconductor Wafer Cleaning System	US	08/908,330	8/7/1997	6/1/1999	5,908,509
Semiconductor Wafer Cleaning System	US	08/908,345	8/7/1997	12/7/1999	5,996,595
Semiconductor Wafer Cleaning System	US	08/910,033	8/11/1997	9/14/1999	5,950,645
Semiconductor Wafer Cleaning System	US	09/694,938	10/23/2000	4/30/2002	6,378,534
Single Chamber Megeasonic Energy Center	US	07/598,909	10/16/1990	9/22/1992	5,148,823
Single Wafer Megeasonic Semiconductor Wafer Processing System	US	07/598,426	10/16/1990	2/25/1992	5,090,432
Single Wafer Megeasonic Semiconductor Wafer Processing System	US	07/809,799	12/18/1991	2/15/1994	5,286,657
Spray Jet Cleaning Apparatus and Method	US	11/745,866	5/8/2007		
Substrate Process Tank with Acoustical Source Transmission and Method of Processing Substrate	US	10/699,042	10/31/2003	10/18/2005	6,955,727
Substrate Processing Device	US	09/308,850	5/24/1999	2/20/2001	6,189,552
System and Method for Drying a Rotating Substrate	US	11/624,445	1/18/2007		
System and Method for Point-of-Use Filtration and Purification of Fluids Used in Substrate Processing	US	10/895,511	7/20/2004	12/25/2007	7,311,847
System and Method for Processing a Substrate Utilizing a Gas Stream for Particle Removal	US	11/841,427	8/20/2007		
System and Method for Selective Etching a Silicon Nitride During Substrate Processing	US	10/585,229	4/20/2007		
System and Method of Clearing Substrates Using a Subambient Process Solution	US	11/544,802	10/6/2006		
System and Method of Determining the Operating Frequency at Which to power a Transducer	US	12/059,602	3/31/2008		
System and Method of Processing Substrates Using Sonic Energy Having Cavitation Control	US	11/454,447	6/15/2006		
System for Removal of Photoresist Using Sparger	US	10/052,823	1/17/2002	11/18/2003	6,649,018
System for Removal of Photoresist Using Sparger	US	10/634,440	8/5/2003	3/8/2005	6,863,836
Transducer Assembly Incorporating a Transmitter Having Through Holes, and Method and System for Cleaning a Substrate Utilizing the Same	US	11/777,252	7/12/2007		
Vapor Drying System and Method	US	09/227,637	1/8/1999	12/11/2001	6,328,809
Vapor Jet Dryer Apparatus and Method	US	07/837,221	2/18/1992	7/13/1993	5,226,242
Wafer Cleaning System	US	08/724,518	9/30/1996	3/21/2000	6,039,059
Wafer Cleaning System	US	09/057,182	4/8/1998	10/31/2000	6,140,744

Title	Country	Application Number	Application Date	Issue Date	Patent Number
Water Cleaning System	US	09/643,328	8/22/2000	10/2/2001	6,140,744
Water Cleaning System	US	09/953,504	9/13/2001	10/15/2002	6,463,938
Water Cleaning System	US	10/243,463	9/12/2002	1/27/2004	6,681,782
Water Cleaning System	US	10/243,486	9/12/2002	2/3/2004	6,684,891
Water Cleaning System	US	10/726,774	12/3/2003	10/10/2006	7,117,876
Water Cleaning System	US	11/275,907	3/15/2006	9/11/2007	7,268,469
Water Cleaning System	US	11/386,634	3/22/2006	5/1/2007	7,211,932
Water Cleaning System	US	11/839,885	8/16/2007		
Water Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature	US	09/324,813	6/21/1999		

TRADEMARK

REEL: 006253 FRAME: 0648

RECORDED: 01/19/2018